

Tool ID: 802  
Tool Location: 111A

Equipment Information Sheet  
Dicing Saw - DISCO

Manager:

Backup:

Backup:

Sam Wright

Michael Skvarla

John Treichler

607-254-4836

607-254-4674

607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Do not operate with open covers

USAGE RESTRICTIONS

- No buddy system restrictions apply
- Check with tool manager for wafers thicker than 1 mm

SCHEDULING/SIGN-UP RESTRICTIONS

- Maximum 2 hour reservation limit

Minimum Tool Time: 30 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No GaAs substrates allowed.

Last Updated: 07/21/2020